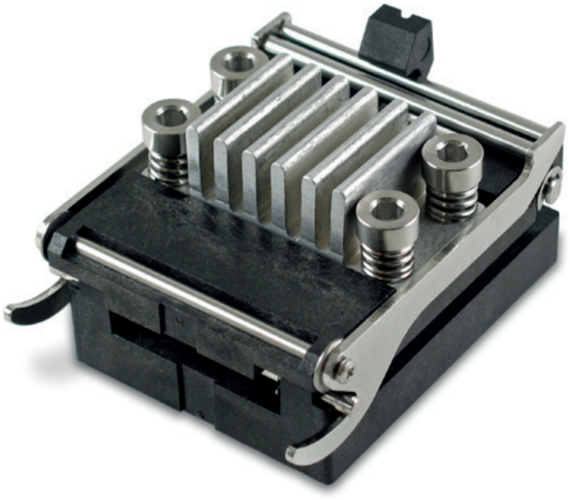
ES Micro Series H-Pin Socket

Accelerated life testing solution



Burn-in sockets using H-Pin technology for high-reliability testing of next-generation IC packages

ES Micro Series Socket is a technological advancement in the burn-in socket segment, with a dual latch clamshell lid to provide co-planar pressure on the DUT when the lid is actuated.

The inclusion of the patented H-Pin contact technology in the ES Micro-Series socket provides market-leading electrical performance in the smallest footprint for the highest possible parallelism on a burn-in board. This series is compatible with standard heaters and temperature sensors.

Benefits

- Configurable design, In-house tooling and molds allow for the lowest cost of test.
- An extensive catalog of standard parts reduces cost and lead time.
- Double-latching clamshell provides ease of use during operation and clearance for lid operation.
- Exceptional electrical performance provides wide RF bandwidth.

Feature Options

- LGA, BGA, and package on package
- Spring loaded plunger
- Heat sink
- HAST venting features
- Integrated thermal control with heater and sensor
- Reverse seating plane
- Max component clearance under the DUT
- High temperature materials for above 200 °C applications

ES Micro Series socket specifications

Mechanical properties

- **Pitch**: ≥0.30 mm
- **Package size for BGA**: 4 mm to 22 mm
- **Pin count**: 1190
- **Temperature**: –55 °C to 260 °C

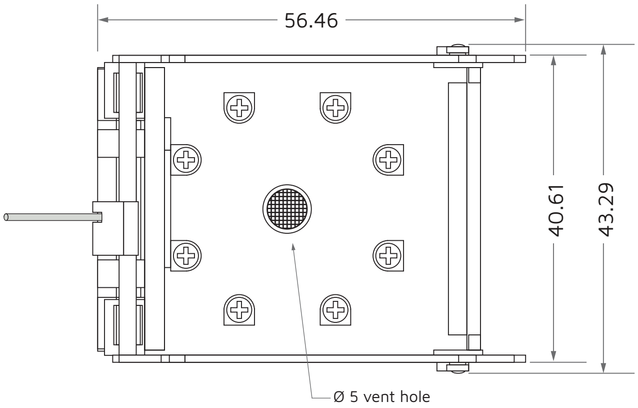
Electrical properties

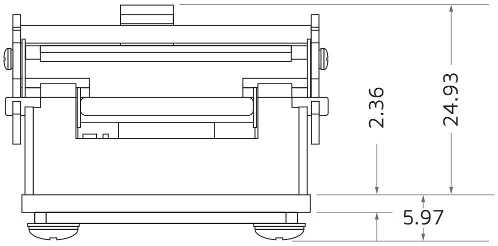
- **Contact resistance**: 35 mΩ
- **Current carrying capacity**: up to 2.5 A

Materials

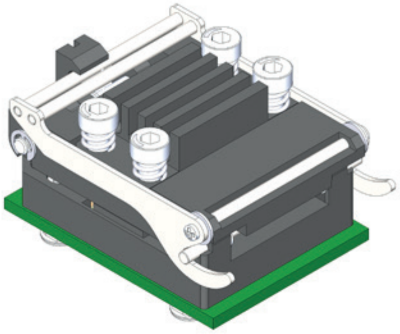
- **Contact**: BeCu/Au plated
- **Spring**: SS/Au plated
- **Socket**: Engineering plastics

ES Micro Series socket dimensions

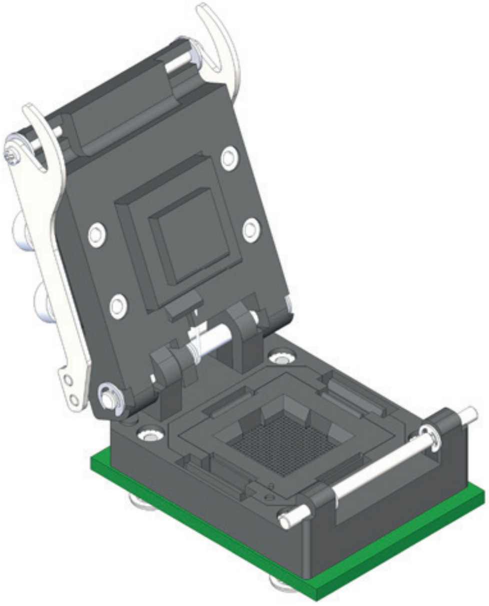




Dimensions are in mm.



Heat sink, heater, and RTD



Spring-loaded plunger

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